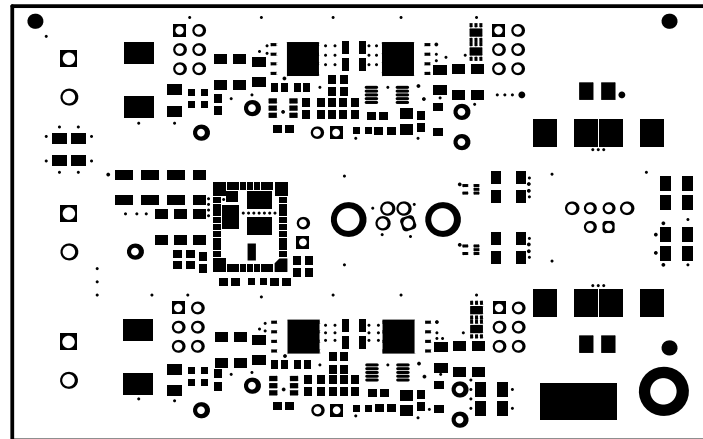
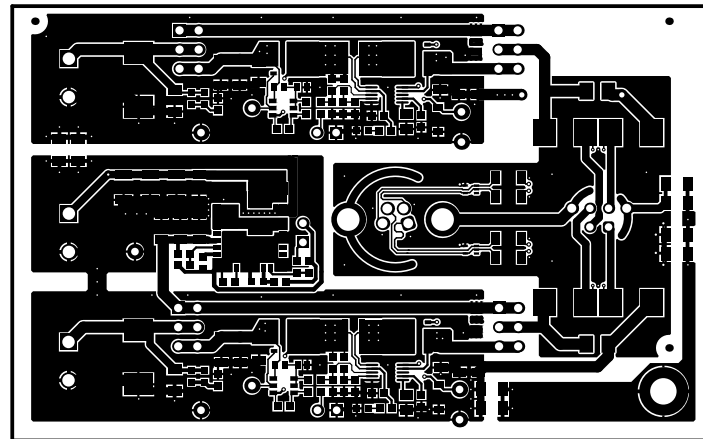


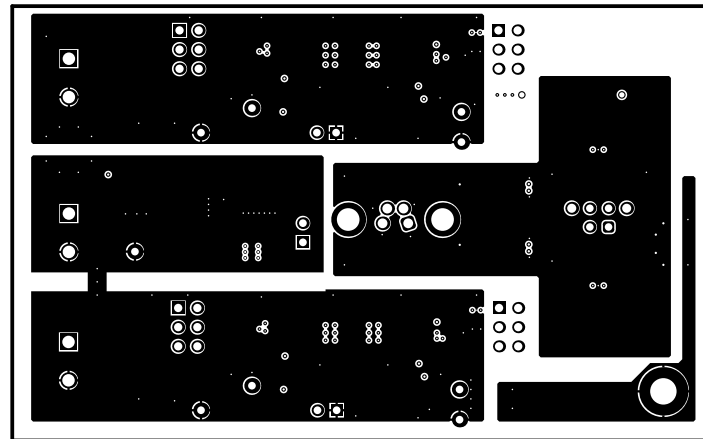
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01461		
PLOT NAME = Top Overlay	GENERATED : 09.11.2017 13:21:58	TEXAS INSTRUMENTS	



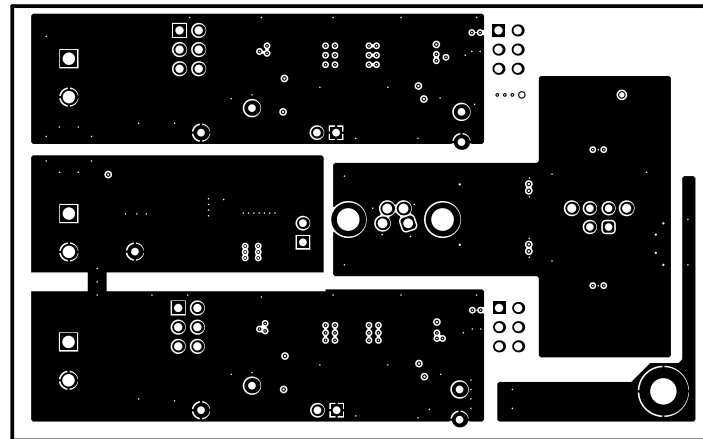
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01461		
PLOT NAME = Top Solder Mask	GENERATED : 09.11.2017 13:21:59	TEXAS INSTRUMENTS	



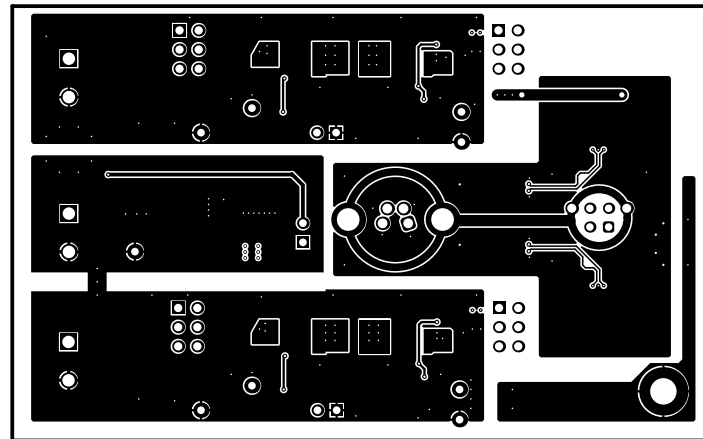
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01461		
PLOT NAME = Top Layer	GENERATED : 09.11.2017 13:22:01	TEXAS INSTRUMENTS	



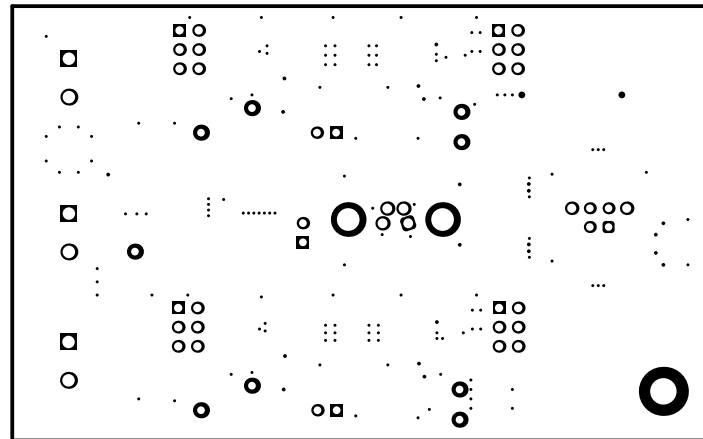
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Mid Layer 1	TID #: TIDA-01461		
PLOT NAME = Signal Layer 1	GENERATED : 09.11.2017 13:22:02	TEXAS INSTRUMENTS	



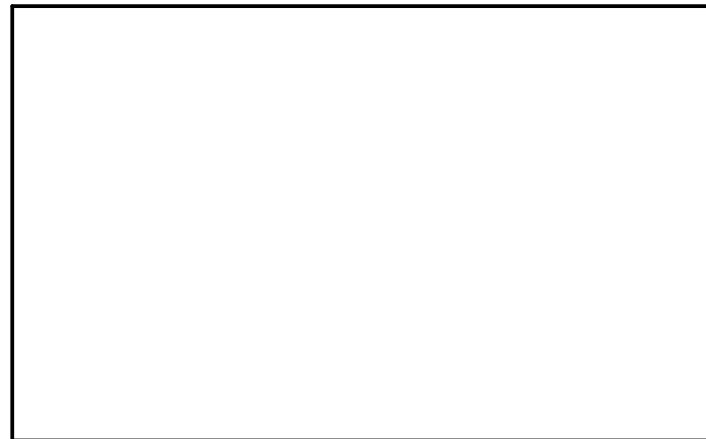
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Mid Layer 2	TID #: TIDA-01461		
PLOT NAME = Signal Layer 2	GENERATED : 09.11.2017 13:22:03	TEXAS INSTRUMENTS	



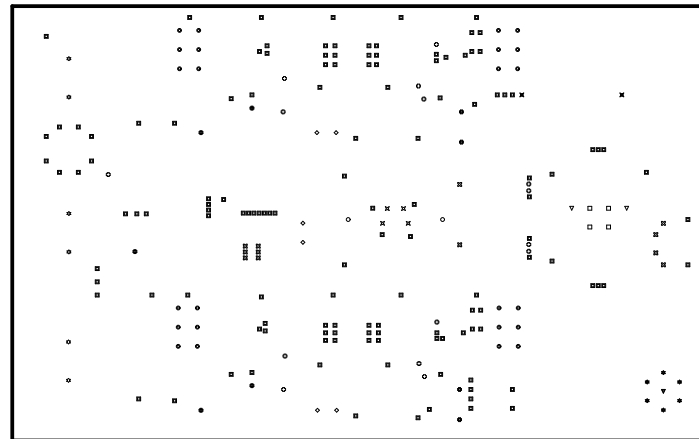
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01461		
PLOT NAME = Bottom Layer	GENERATED : 09.11.2017 13:22:04	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01461		
PLOT NAME = Bottom Solder Mask	GENERATED : 09.11.2017 13:22:05	TEXAS INSTRUMENTS	

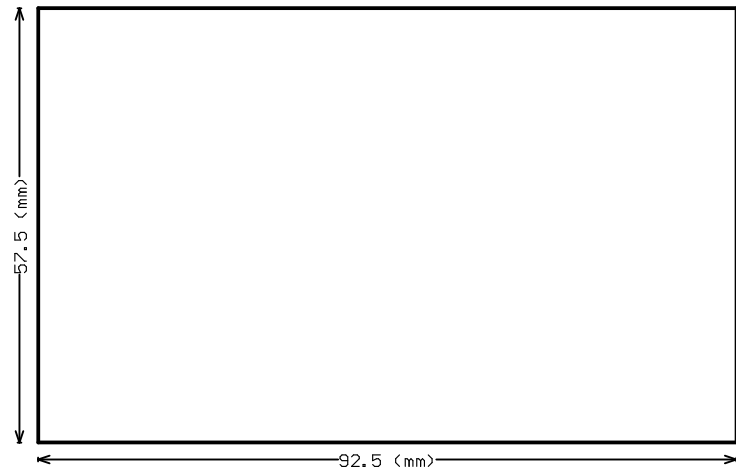


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01461		
PLOT NAME = Bottom Overlay	GENERATED : 09.11.2017 13:22:07	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
■	134	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	12	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	15	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	6	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	2	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	9	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
◇	6	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊖	24	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	6	64.96mil (1.650mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	118.11mil (3.000mm)	PTH	Round	Top Layer - Bottom Layer	
▽	1	137.80mil (3.500mm)	PTH	Round	Top Layer - Bottom Layer	
	227 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01461		
PLOT NAME = Drill Drawing	GENERATED : 09.11.2017 13:22:08	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01461	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01461		
PLOT NAME = Board Dimensions	GENERATED : 09.11.2017 13:22:10	TEXAS INSTRUMENTS	

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